

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Harald Böttner, et al.

Assignees: Infineon Technologies AG, et al.

Title: "Solder, Microelectromechanical Component
And Device, And A Process For Producing A
Component Or Device"

Serial No. 10/789,423

File Date: 2/27/2004

Examiner: unknown

Art Unit: 2811

Date: July 19, 2004Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450PRELIMINARY AMENDMENT

Dear Sir:

Please amend the above-identified application to
correct informalities and/or typographical errors. No new
matter is believed to be added.